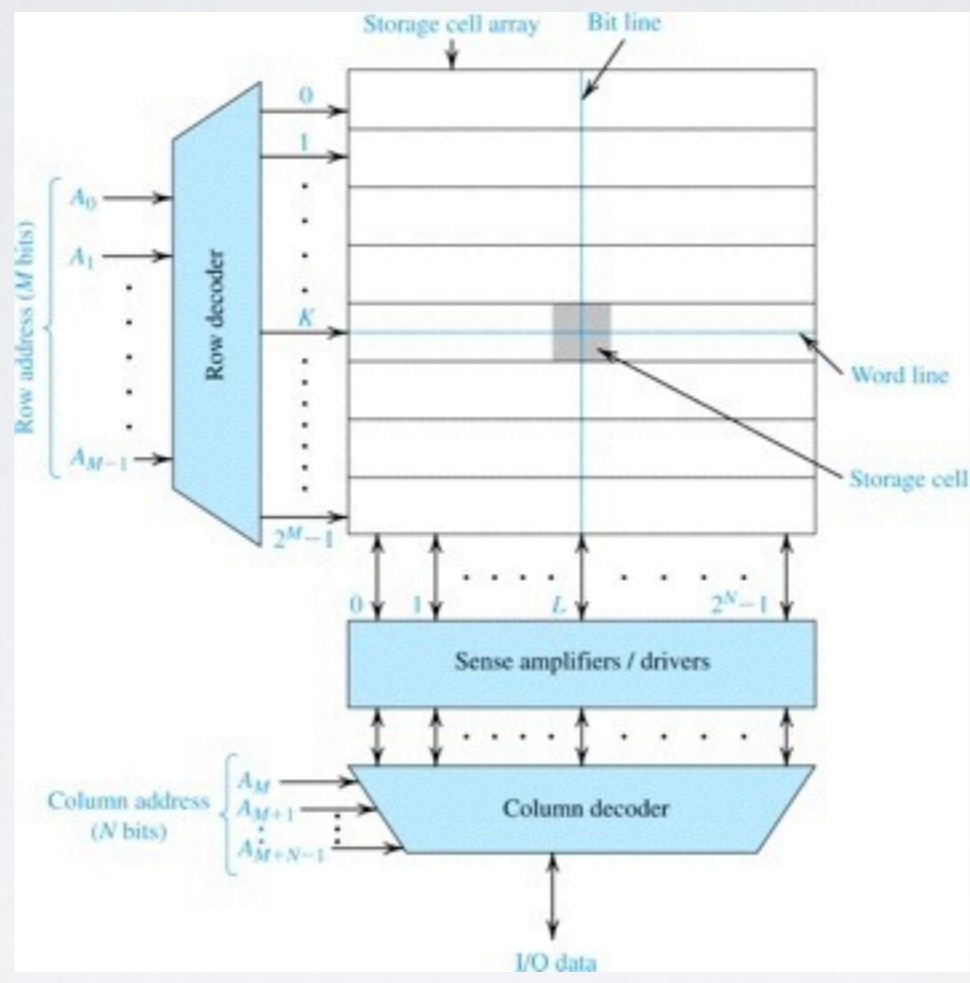
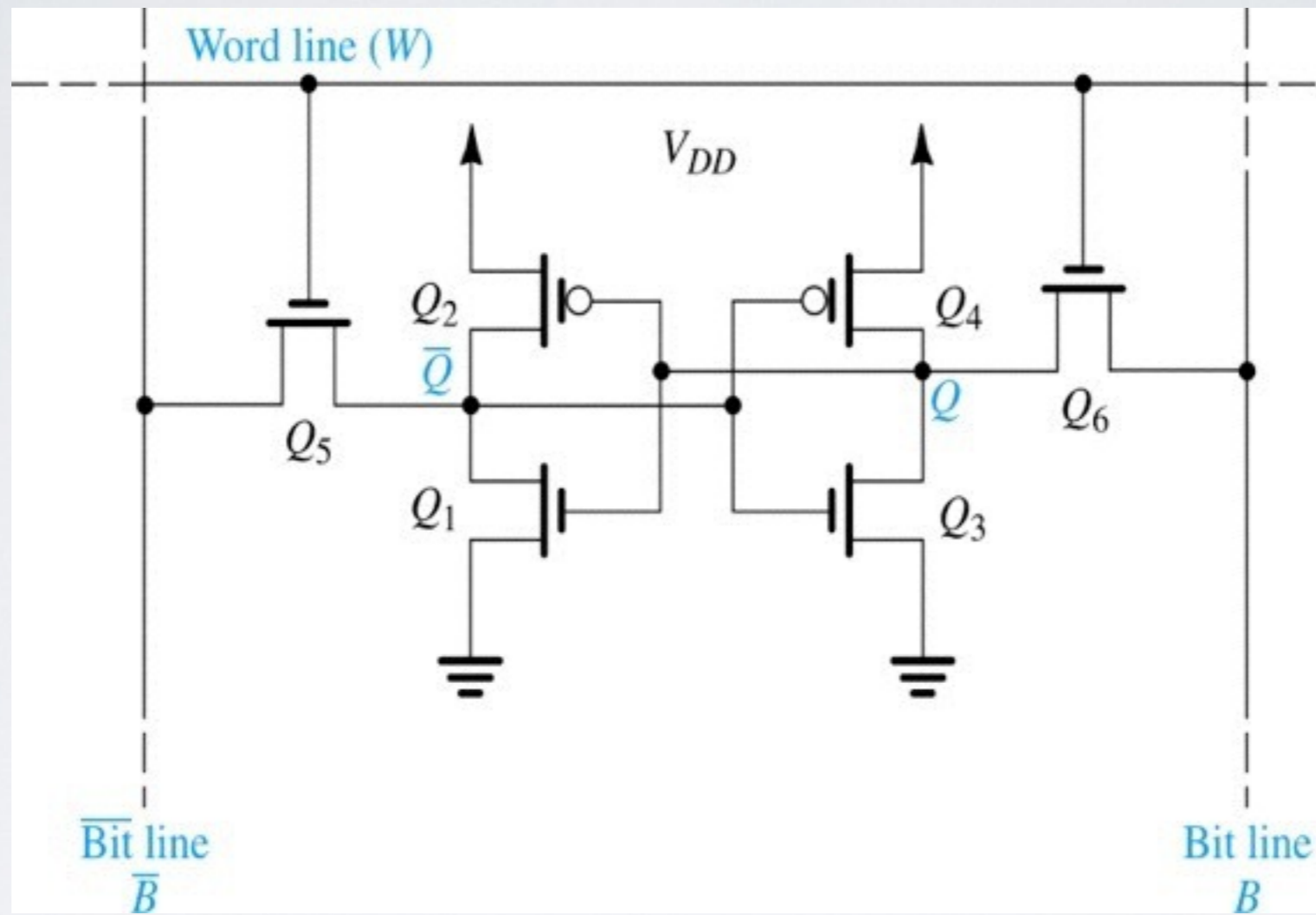


# STATIC & DYNAMIC RAMS

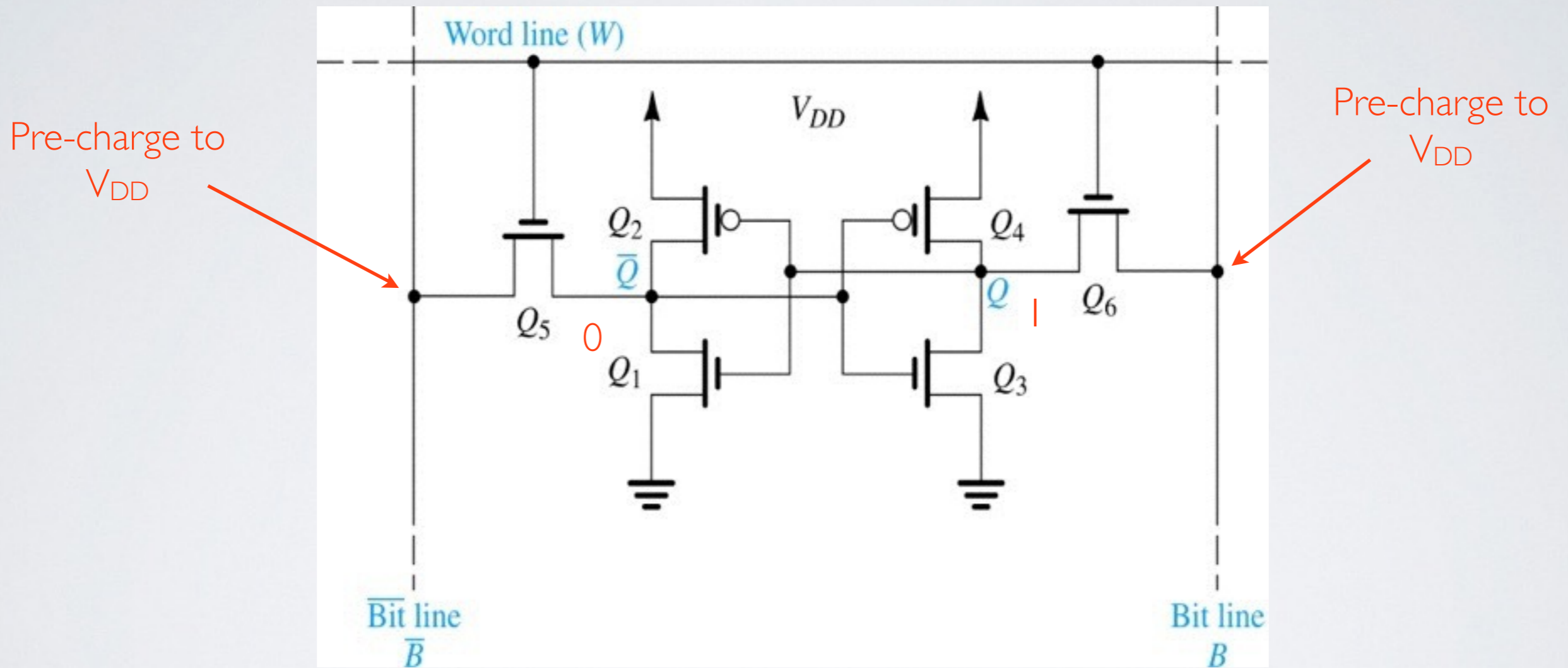
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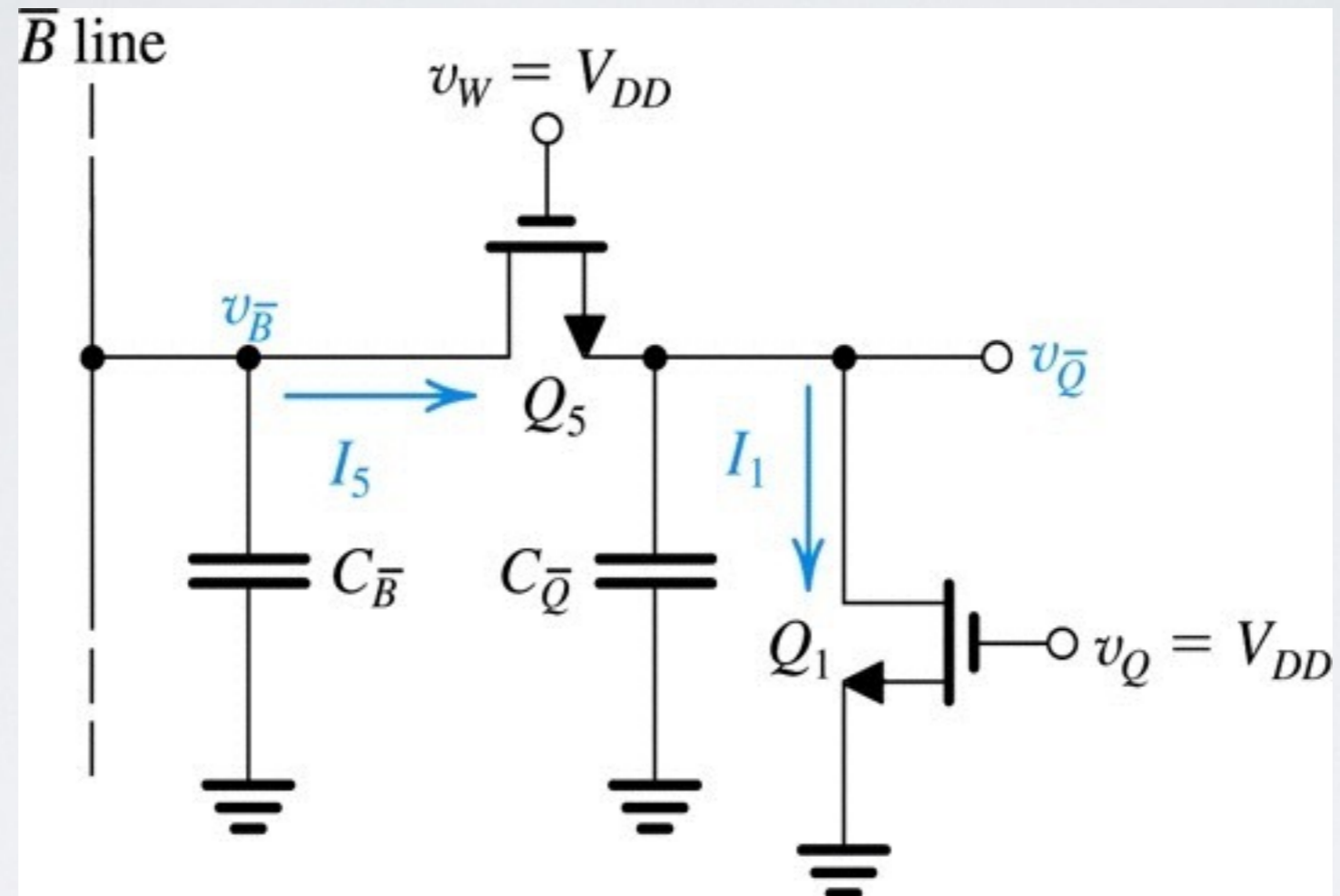
# READING



# READING

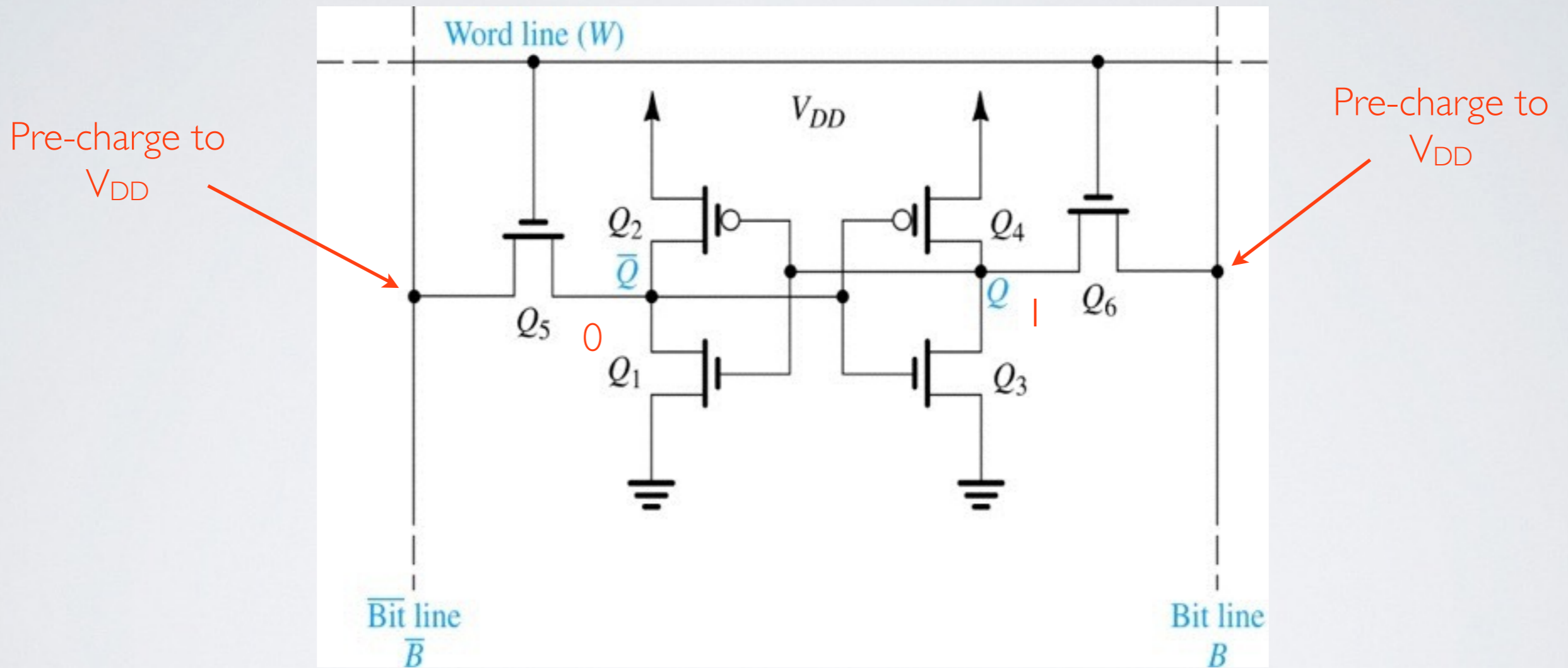


# READING

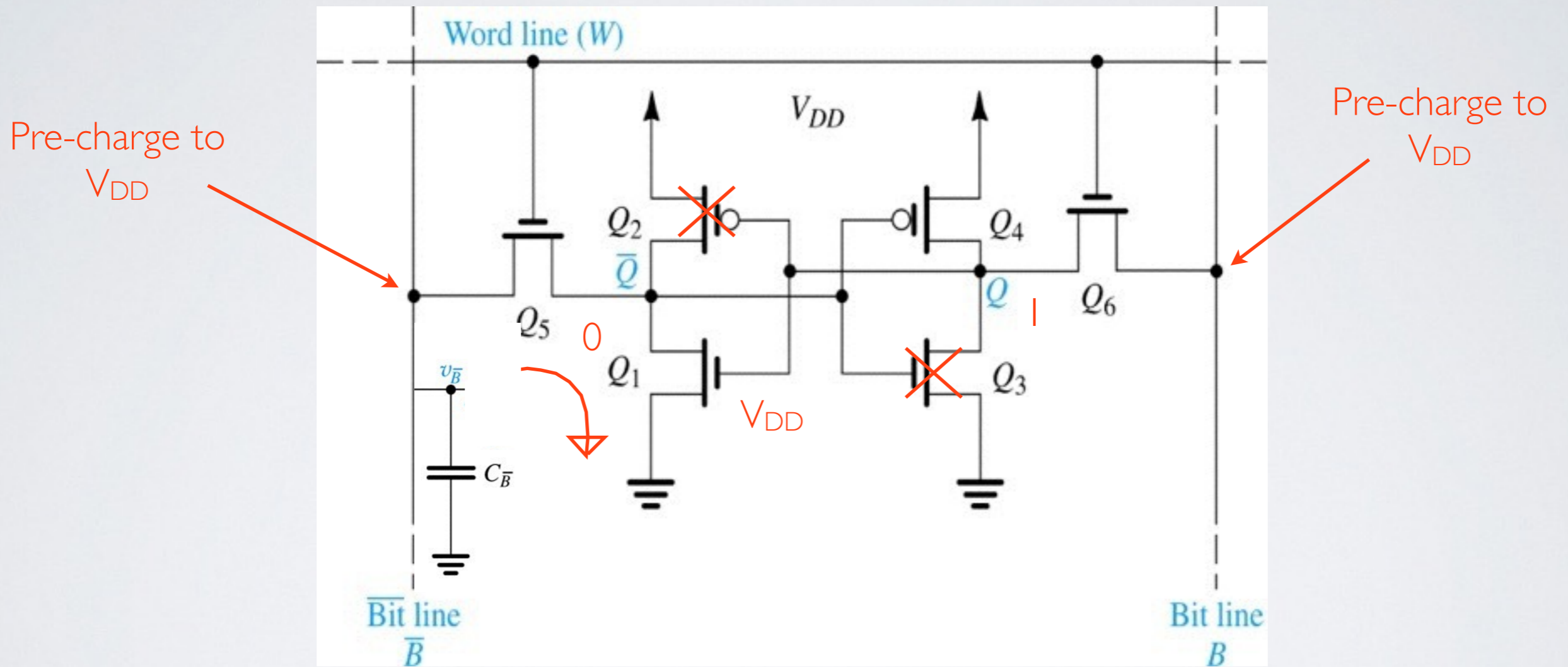




# READING



# READING



# READING

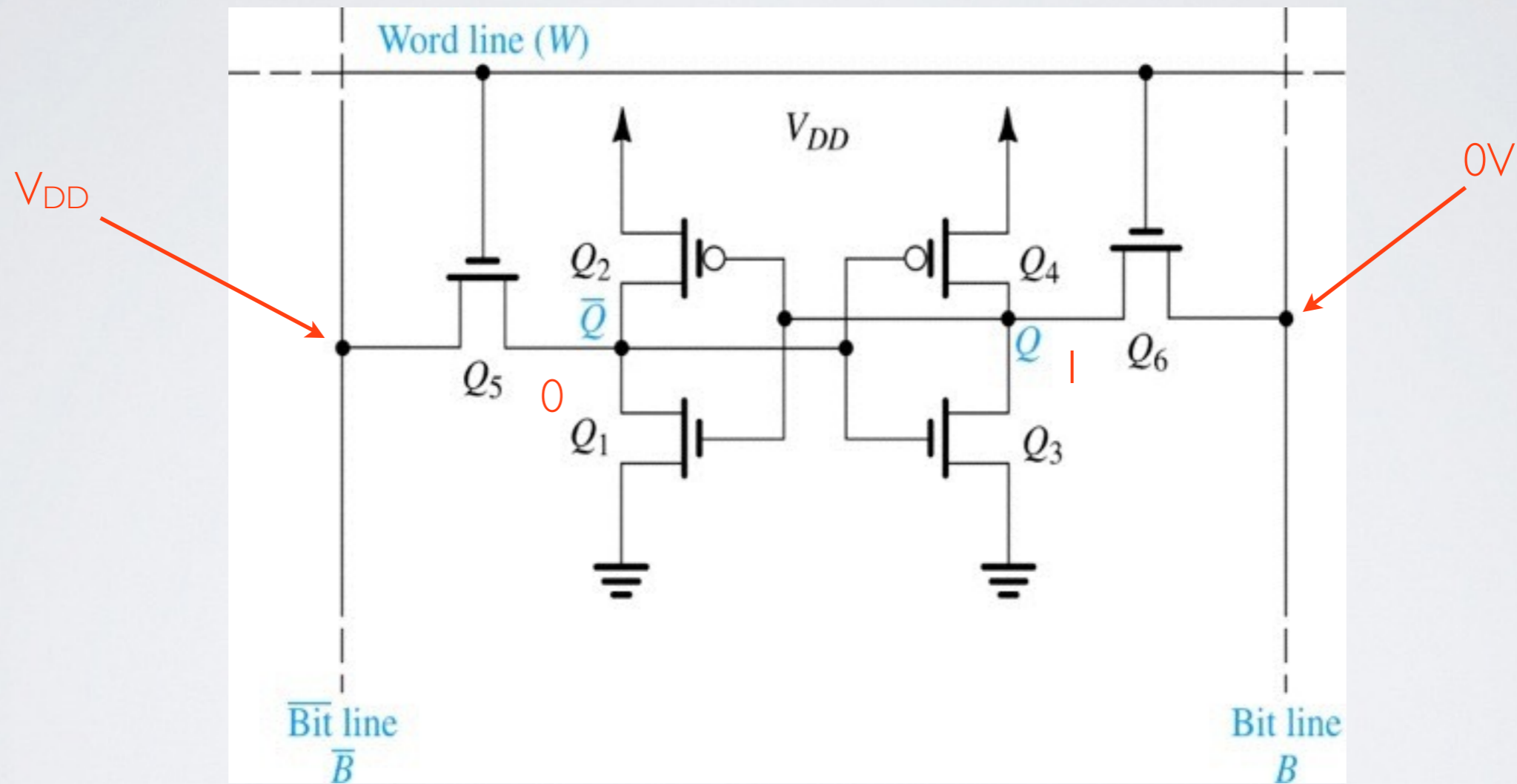
## Example

A CMOS SRAM cell shown in the previous slide is fabricated in a 0.18- $\mu\text{m}$  process for which  $V_{tn} = |V_{tp}| = 0.5\text{V}$  and  $V_{DD} = 1.8\text{V}$ . The inverters have  $(W/L)_n = 0.27\mu\text{m}/0.18\mu\text{m}$ . Assume that a cell containing a 1 must be read.

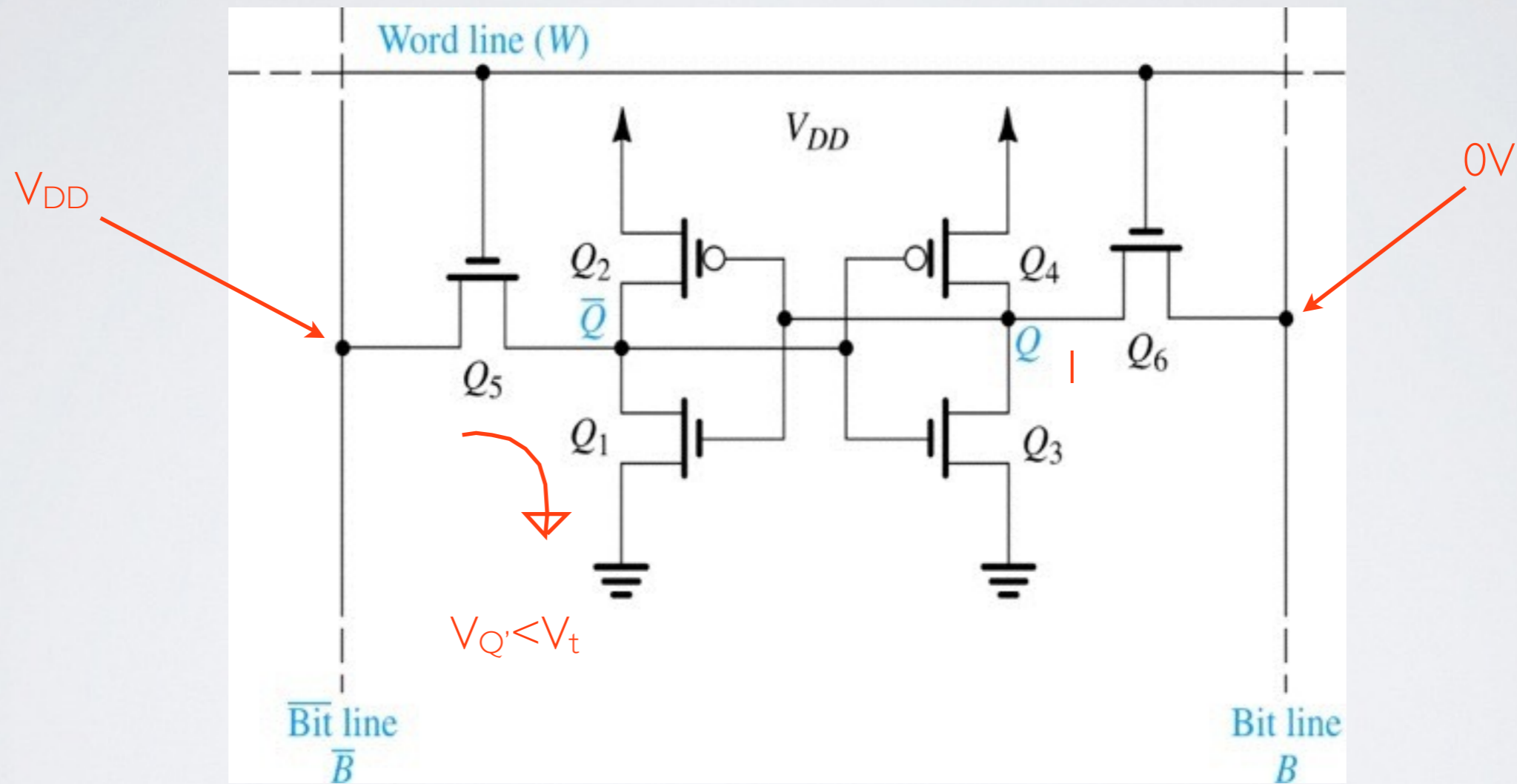
- (a) Determine the maximum value of  $(W/L)_5$  to ensure that the cell will not change state.
- (b) Determine the read delay  $\Delta t$  in two cases: (i)  $(W/L)_5 = 2.5$  and (ii)  $(W/L)_5 = 1.5$ . Let  $\mu_n C_{ox} = 300\mu\text{A}/\text{V}^2$ ,  $C_{B'}$  = 2pF, and the minimum change in voltage required by the sense amplifier be  $\Delta V = 0.2\text{V}$ .



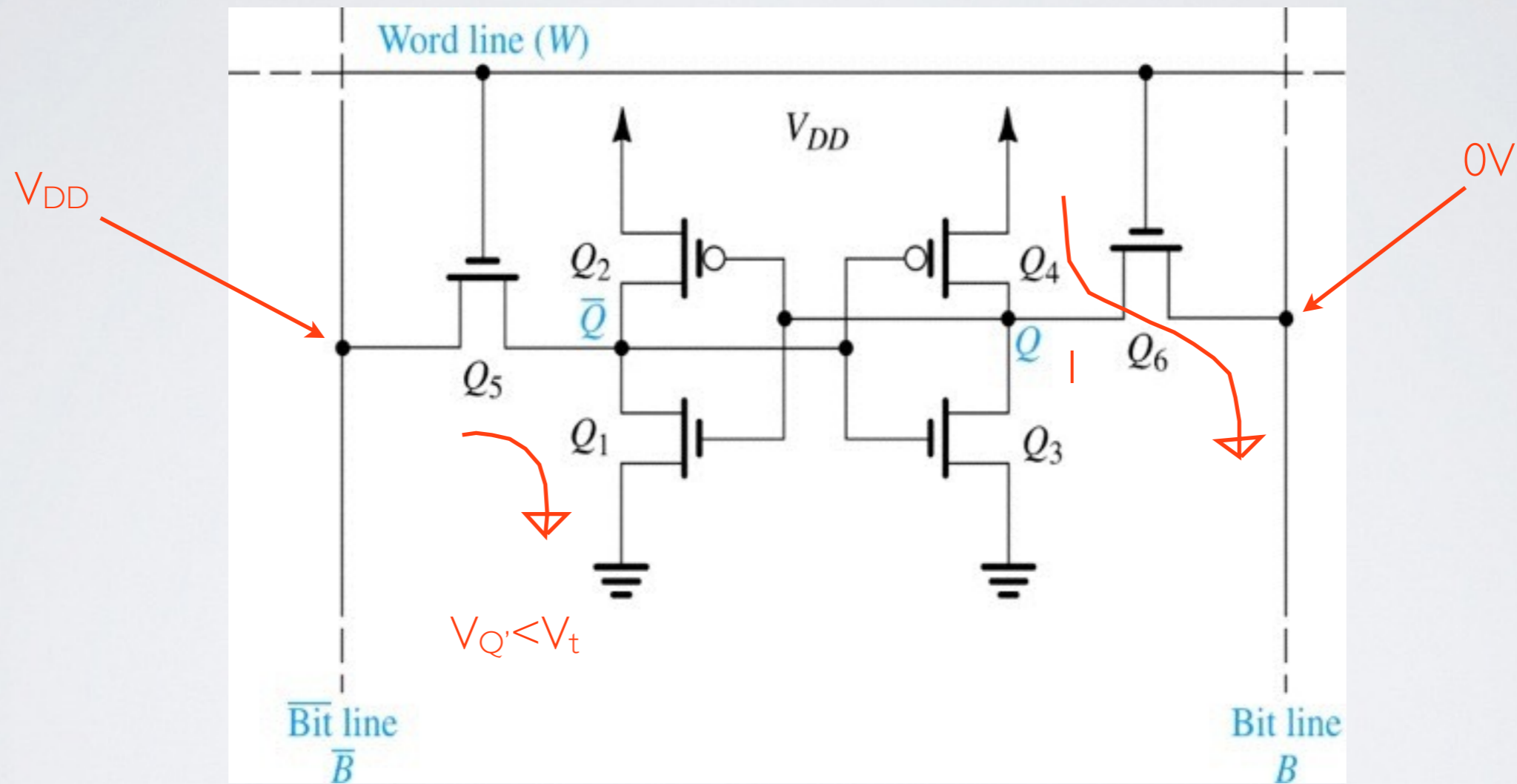
# WRITING



# WRITING



# WRITING



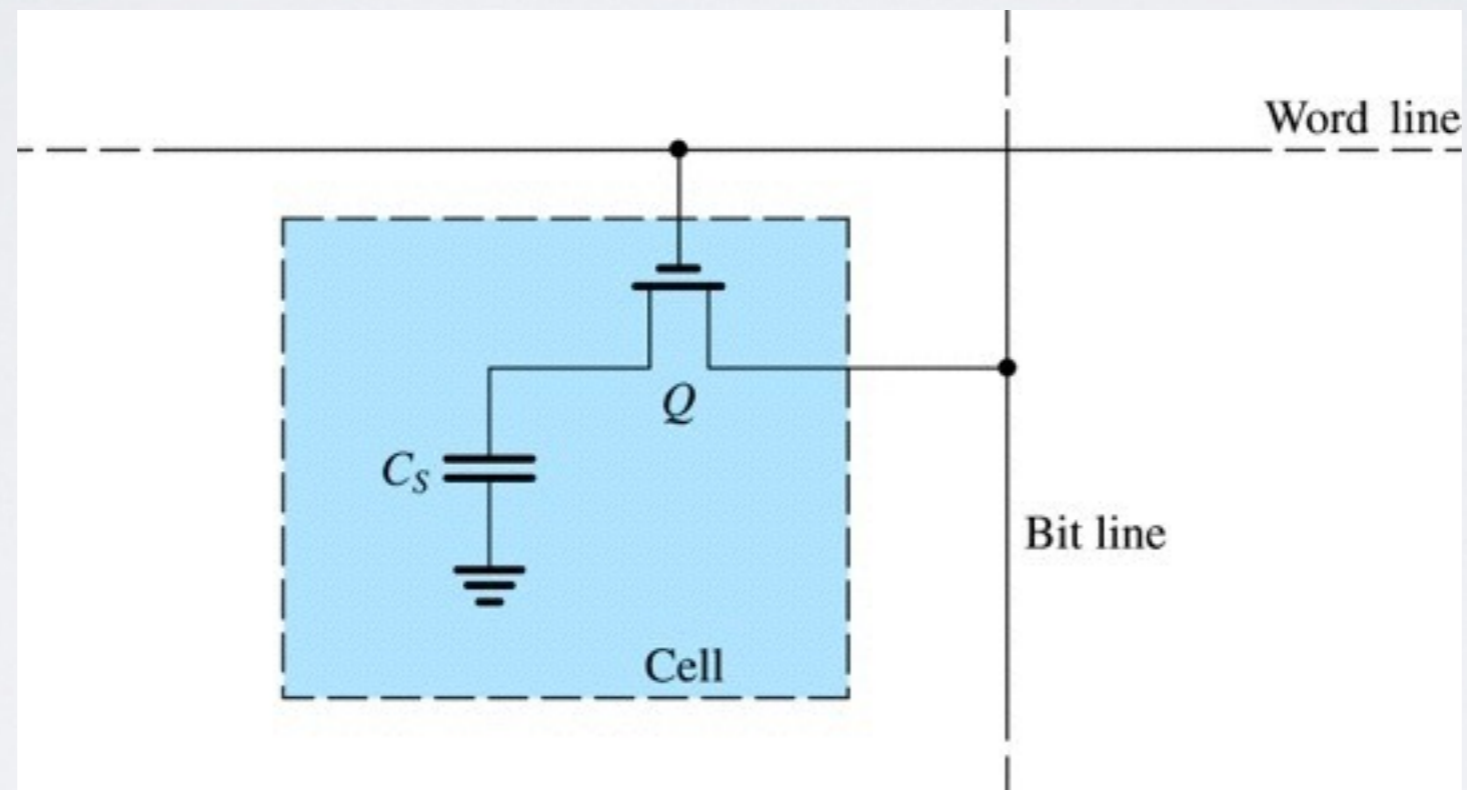
$\therefore$  Select  $(W/L)_4$  so that  $V_Q < V_t$

# WRITING

## Example

A 0 must be stored on the SRAM cell described in the previous example, which initially contains a 1. Determine the maximum value of  $(W/L)_4$  needed to ensure that the cell will change state.

# DYNAMIC RAM





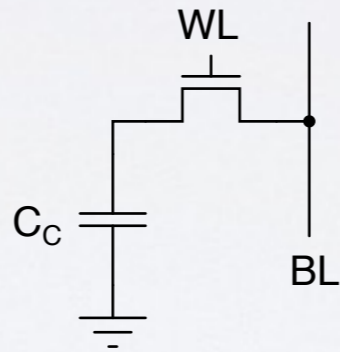
$$C_S V_{CS} + C_B \frac{V_{DD}}{2} = (C_B + C_S) \left( \frac{V_{DD}}{2} + \Delta V \right)$$

$$\Delta V = \frac{C_S}{C_B + C_S} \left( V_{CS} - \frac{V_{DD}}{2} \right)$$



**Figure 16.19** When the voltage of the selected word line is raised, the transistor conducts, thus connecting the storage capacitor  $C_S$  to the bit-line capacitance  $C_B$ .

1. (25 points) For the following dynamic RAM circuit.  $C_C = 50fF$ ,  $V_{DD} = 5V$ , and  $V_t = 1.4V$  (including body effect). There are  $n$  cells connected to the bit line, and each cell represents a capacitive load on the bit line of  $2fF$ . The sense amplifier and other circuitry attached to the bit line has a  $20fF$  capacitance, so that the total bit line capacitance is  $2n + 20$ , in  $fF$ . Consider a reading process in which the bit line is pre-charged to a voltage of  $V_{DD}/2$ . What is the maximum number of cells that can be attached to a bit line while ensuring a minimum change on the bit line voltage, once steady state is reached, of  $0.1V$ ?



ANSWER: The bit line capacitance is  $C_{BL} = n \times 2fF + 20fF$ . Due to charge sharing,

$$V_f (C_{BL} + C_C) = 2.5V \times C_{BL} + V_{i,C} \times C_C$$

where  $V_{i,C}$  represents the initial voltage in the cell.

Let  $V_f = 2.5V + \Delta V$  and consider a cell containing a logic-1, so that  $V_{i,C} = 5V - 1.4V = 3.6V$ . then

$$\Delta V (C_{BL} + C_C) = 2.5V \times C_{BL} + V_{i,C} \times C_C - 2.5V (C_{BL} + C_C)$$

$$\Delta V (C_{BL} + C_C) = 2.5V \times C_{BL} + V_{i,C} \times C_C - 2.5V \times C_{BL} - 2.5V \times C_C$$

$$0.1V (n \times 2fF + 20fF) = (3.6V - 2.5V - 0.1V) \times 50fF$$

$$n = \frac{10 \times 50fF - 20fF}{2fF} = 240$$

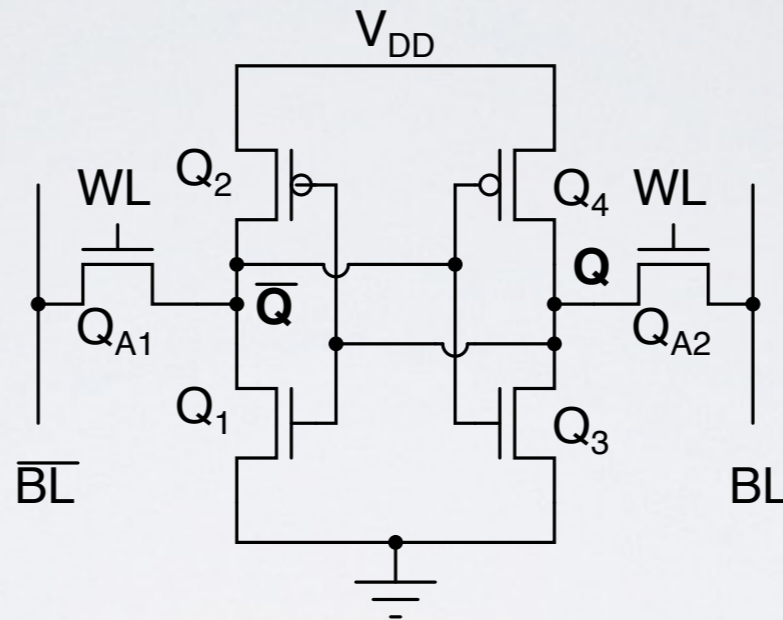
Now repeat, but this time consider a cell containing a logic-0. The procedure is similar, but  $V_{i,C} = 0V$ .

$$-0.1V (n \times 2fF + 20fF) = -2.4V \times C_C$$

$$n = \frac{24 \times 50fF - 20fF}{2fF} = 590$$

So  $n = \boxed{240}$ .

2. (25 points) For the following static RAM circuit,  $(W/L)_{1,3} = 2/1$  and  $(W/L)_{A1,A2} = 4/5$ ,  $V_{DD} = 3.3V$ ,  $\mu_n C_{OX} = 4\mu_p C_{OX} = 300\mu A/V^2$ ,  $V_{t0} = 0.6V$  for NMOS transistors and  $V_{t0} = -0.6V$  for PMOS transistors,  $\gamma = 0.5\sqrt{V}$  and  $2\phi_F = 0.6V$ .



Use the average current method to determine the minimum time needed to read the cell if a change  $\Delta V_{BL} = 100mV$  is needed by a sense amplifier. The bit line capacitance is  $C_{BL} = 0.1pF$  and a logic-0 is stored in the cell. Assume that the bit line was pre-charged with  $3.3V$  and that during the reading process  $V_Q$  remains at or below the threshold voltage. Neglect the cell's internal capacitances.



ANSWER: The voltage reduction happens when current flows through  $Q_{A2}$  and  $Q_3$ . Assume  $v_{DS,3} \leq 0.6V$  so that the cell's data is not disturbed. We can use the average current method. At point 1,  $V_{Q3}$  is very close to  $0V$ ,  $Q_{A2}$  operates in saturation mode, and

$$i_1 = \frac{300\mu A/V^2}{2} \left(\frac{4}{5}\right) (3.3V - 0.6V)^2 = 875\mu A$$

At point 2,  $V_{Q3} = 0.6V$ . Thus,  $Q_3$  and  $Q_{A2}$  operate in triode and saturation mode, respectively, and

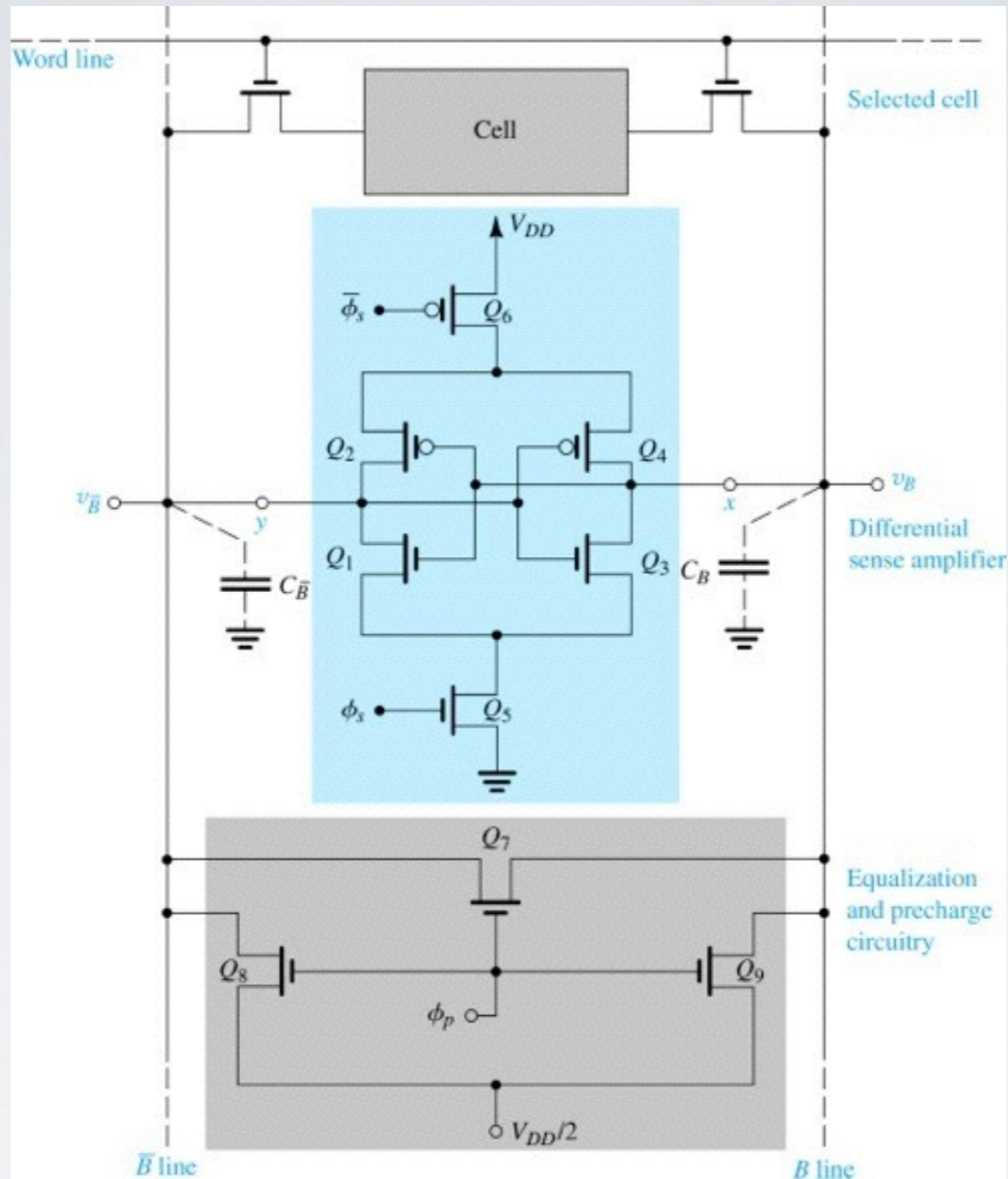
$$V_{t,A1} = 0.6V + (0.5\sqrt{V}) \left(\sqrt{0.6V + 0.6V} - \sqrt{0.6V}\right) = 0.76V$$

$$I_2 = \frac{300\mu A/V^2}{2} \left(\frac{4}{5}\right) (3.3V - 0.6V - 0.76V)^2 = 452\mu A$$

The average current is  $(452\mu A + 875\mu A)/2 = 663\mu A$  and

$$\Delta t = 0.1pF \times \frac{0.1V}{663\mu A} \simeq \boxed{15ps}$$





**Figure 16.20** A differential sense amplifier connected to the bit lines of a particular column. This arrangement can be used directly for SRAMs (which utilize both the  $B$  and  $\bar{B}$  lines). DRAMs can be turned into differential circuits by using the “dummy-cell” arrangement shown later (Fig. 16.22).